



AUTOTRONIK

Fertigungssysteme für die Elektronikindustrie

AT530



Precision

Flexible

Economic

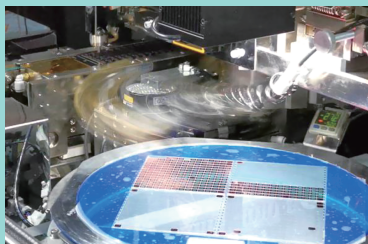
High Performance

AT530 IR Filter High Speed Bonder

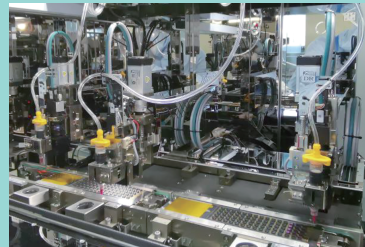
Specifications

- High productivity up to 5000+ pcs/hour
- 3 Simultaneous Gel Dispense Heads
- X/Y Repeatability Accuracy $\pm 0.015\text{mm}$
- R-axis Accuracy $\pm 0.2^\circ$
- Real-time Bond Post Checking (BPC)
- High Reliability for Continuous Production
- Real-time Gel-trail Inspection
- User Friendly Software Control

Highly accurate and stable



X & Y Placement Accuracy less than $\pm 15\mu\text{m}$, R Accuracy as $\pm 0.2^\circ$

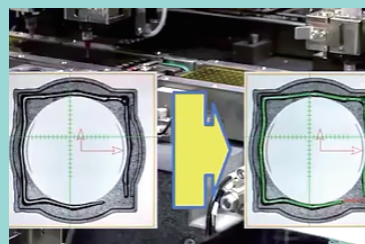
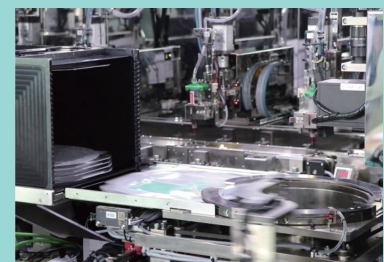


3 Gel Dispensing Heads

High speed as 5000+ pcs per hour achieved by 3 simultaneous Gel Dispensing Heads.

Auto-loading System

Auto-loading system for the wafer flange load and unload from magazine, maximum up to 25 storeys.



Real-time Gel-trail Inspection

Real-Time Gel-Trail inspection to guarantee any failed dispense shall be ignored to reduce wastage.

We reserve the right to make changes without notice